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Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		BAT17 Part Description						
								Nexperia DHAM
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage ^[1]	1000 hours	116	9280	0		
	тс	150000 4104						
	Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000	170	12600	0		
# A4	Temperature Cycling		1000 cycles	170	13600	0		
	AC	JESD22-A102						
	AL Autoclave	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	0.5.1	170	10000			
# A3 alt	Autoclave	riessure – 203 kra (23.7 psia)	96 hours	170	13600	0		
	H3TRB	JESD22-A101						
	H31KB High Humidity High	Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of						
# A2 alt	Temperature Reverse Bias		1000 hours	170	13600	0		
# AZ alt			1000 Hours	170	13000	U		
	IOL	MIL-STD-750 Method 1037						
# A5	Intermittent Operating Life	ton = toff, devices powered to insure ΔT_j = 100 °C for 15000 cycles	1000 hours	170	12600	0		
+ A5	Internittent Operating Life		1000 hours	170	13600	0		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat		10 s	130	3900	0		
# C8	SD	200 0 - 5 0	10.2	130	2900	0		
	Solderability	J-STD-002		262	2620	0		
	•	des have to be considered (thermal runaway).		363	3630	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
	Beneticity	200	5		21152.05

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